



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



## Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

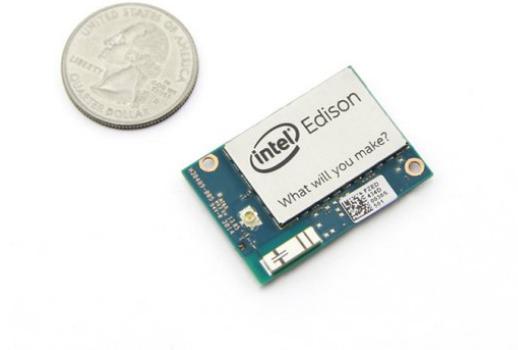
Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



## Intel® Edison

SKU: 102990161



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### Description

#### Brief Introduction:



The Intel® Edison development platform is bringing down barriers in the world of wearables and IoT technology.

**Dimensions: 32.5 x 25.0 x 3.9 mm**

#### Main Features:

- Uses a 22nm Intel® SoC that includes a dual core, dual threaded Intel® Atom™ CPU at 500MHz and a 32-bit Intel® Quark™ microcontroller at 100 MHz. It supports 40 GPIOs and includes 1GB LPDDR3, 4 GB EMMC, and dual-band WiFi and BTLE on a module slightly larger than a postage stamp.
- The Intel Edison module will initially support development with Arduino\* and C/C++, followed by

NodeJS, Python, RTOS, and Visual Programming support in the near future.

- It includes a device-to-device and device-to-cloud connectivity framework to enable cross-device communication and a cloud-based, multi-tenant, time-series analytics service.

### Specification:

<b>Physica</b>	
Form factor	Board with 70-pin connector
Dimensions	32.5 x 25.0 x 3.9 mm
Operating temperature	0 to 40 degC
Connector	Hirose DF40 Series (1.5mm, 2.0mm, or 3.0mm stack height)
<b>Memory</b>	
Max Memory size	4GB
Memory type	DDR3, Nand Flash
Physical add. Ext.	32-bit
# of DIMMs	0
ECC Memory supported:	NO
<b>External Interfaces</b>	
Total of 40 GPIOs which can be configured as:	
SD Card	1 Interface
UART	2 Controllers
I2C	2 Controllers
SPI	1 Controller with 2 chip selects
I2S	1 Controller
GPIO	Additional 12 (with 4 capable of PWM)
USB 2.0	1 OTG Controller
Clock Output	32 KHz, 19.2 MHz
<b>Major Edison Components</b>	
SoC	22nm Intel SoC includes: a dual core, dual threaded Intel Atom CPU at 500MHz, and a 32-bit Intel Quark microcontroller at 100 MHz
RAM	1 GB LPDDR3 POP memory
Flash Storage	4 GB eMMC
WiFi	Broadcom 43340 802.11 a/b/g/n Dual-band (2.4 and 5 GHz) On board antenna or external antenna SKU configurations
Bluetooth	BT 4.0
<b>Power</b>	
Input	3.3V - 4.5V
Output	100ma @3.3V and 100ma @ 1.8V
Power	Standby (No radios): 13mW Standby (BT 4.0): 21.5mW Standby (WiFi): 35 mW
<b>Firmware + Software</b>	
CPU OS	Yocto Linux v1.6
Development Environments	Arduino IDE Eclipse supporting: C, C++ & Python Intel XDK supporting: NodeJS & HTML5
MCU OS	RTOS
Development Environments	MCU SDK and IDE